



-100V P-Channel MOSFET

● Features

-100V/-30A ,

$R_{DS(ON)} < 58m\Omega @ V_{GS} = -10V$

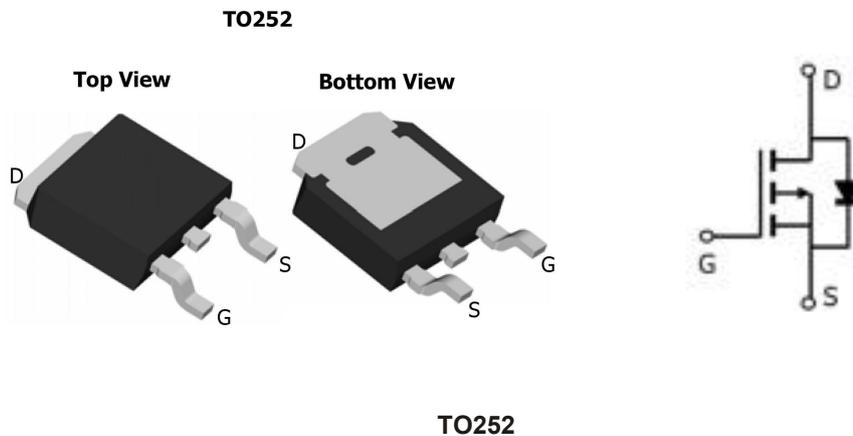
$R_{DS(ON)} < 65m\Omega @ V_{GS} = -4.5V$

Lead Free Available (RoHS Compliant)

● General Description

The FS2245B uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications. It is ESD protected.

● Pin Configuration



● Absolute Maximum Ratings $T_A=25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Maximum	Units
Drain-Source Voltage	V_{DS}	-100	V
Gate-Source Voltage	V_{GS}	± 20	
Continuous Drain Current	I_D	$T_A=25^\circ\text{C}$	-30
		$T_A=100^\circ\text{C}$	-21
Pulsed Drain Current	I_{DM}	-150	A
Avalanche energy $L=1\text{mH}$ <small>note5</small>	E_{AS}, E_{AR}	420	mJ
Maximum Power Dissipation	P_D	120	W
Derating factor		0.8	$\text{W}/^\circ\text{C}$
Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 175	$^\circ\text{C}$

Thermal Characteristics			
Parameter	Symbol	Limit	Units
Thermal Resistance, Junction-to-Case <small>note2</small>	$R_{\theta Jc}$	1.25	$^\circ\text{C}/\text{W}$



● Electrical Characteristics ($T_A=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
Off Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$I_D=-250\mu\text{A}$, $V_{GS}=0\text{V}$	-100	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=-100\text{V}$, $V_{GS}=0$	-	-	1	μA
I_{GSS}	Gate-Body leakage current	$V_{DS}=0\text{V}$, $V_{GS}=\pm 20\text{V}$	-	-	± 10	
On Characteristics ^{note3}						
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}$ $I_D=-250\mu\text{A}$	-1.5	-1.9	-2.5	V
$R_{DS(on)}$	Static Drain-Source On-Resistance	$V_{GS}=-10\text{V}$, $I_D=-15\text{A}$	-	44	58	$\text{m}\Omega$
		$V_{GS}=-4.5\text{V}$, $I_D=-15\text{A}$	-	48	65	
g_{FS}	Forward Trans conductance	$V_{DS}=-50\text{V}$, $I_D=-10\text{A}$	5	-	-	S
Dynamic Characteristics ^{note4}						
C_{iss}	Input Capacitance	$V_{GS}=0\text{V}$, $V_{DS}=-50\text{V}$, $f=1\text{MHz}$	-	8049	-	pF
C_{oss}	Output Capacitance		-	184.5	-	
C_{rss}	Reverse Transfer Capacitance		-	179	-	
Switching Characteristics ^{note4}						
$t_{D(on)}$	Turn-On Delay Time	$V_{GS}=-10\text{V}$, $V_{DD}=-50\text{V}$, $I_D=-15\text{A}$, $R_{GEN}=9.1\Omega$	-	17	-	ns
t_r	Turn-On Rise Time		-	80	-	
$t_{D(off)}$	Turn-Off Delay Time		-	45	-	
t_f	Turn-Off Fall Time		-	65	-	
Q_g	Total Gate Charge	$V_{GS}=-10\text{V}$, $V_{DS}=-50\text{V}$, $I_D=-15\text{A}$		120		nC
Q_{gs}	Gate Source Charge			22		
Q_{gd}	Gate Drain Charge			26.4		
Drain-Source Diode Characteristics						
V_{SD}	Diode Forward Voltage ^{note3}	$I_S=-10\text{A}$, $V_{GS}=0\text{V}$	-	-	-1.2	V
I_S	Diode Forward Current ^{note2}		-	-	-30	A
T_{ON}	Forward Turn-On Time	Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD)				
t_{rr}	Body Diode Reverse Recovery Time	$T_J = 25^\circ\text{C}$, $I_F = -15\text{A}$	-	90	-	ns
Q_{rr}	Body Diode Reverse Recovery Charge	$di/dt = 100\text{A}/\mu\text{s}$ ^{note3}	-	150	-	nC

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, $t \leq 10$ sec.
3. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$.
4. Guaranteed by design, not subject to production
5. EAS condition: $T_J=25^\circ\text{C}$, $V_{DD}=-50\text{V}$, $V_G=-10\text{V}$, $L=0.5\text{mH}$, $R_g=25\Omega$



- Typical Electrical and Thermal Characteristics (Curves)

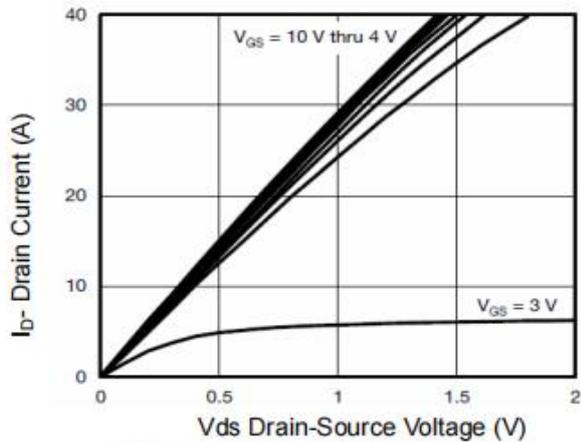


Figure 1 Output Characteristics

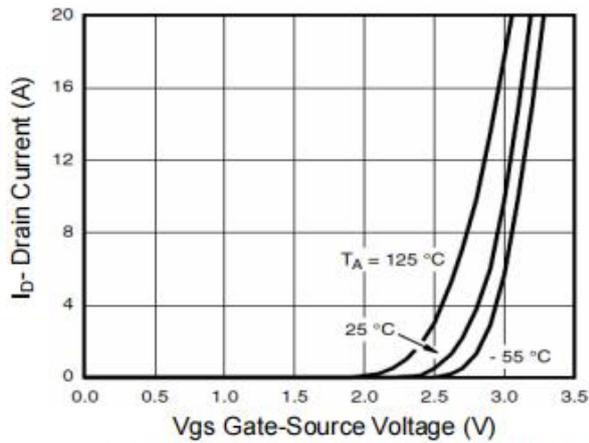


Figure 2 Transfer Characteristics

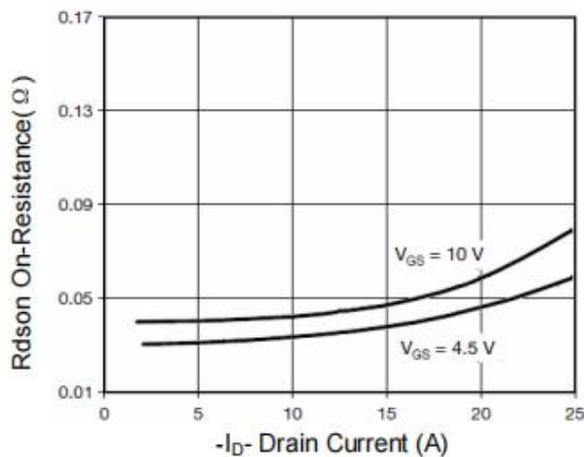


Figure 3 Rds(on)- Drain Current

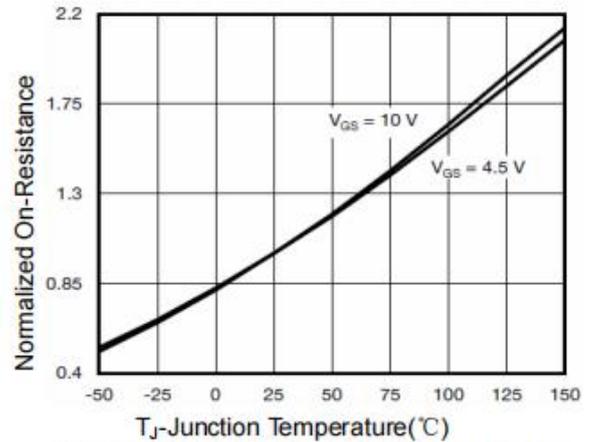


Figure 4 Rds(on)-Junction Temperature

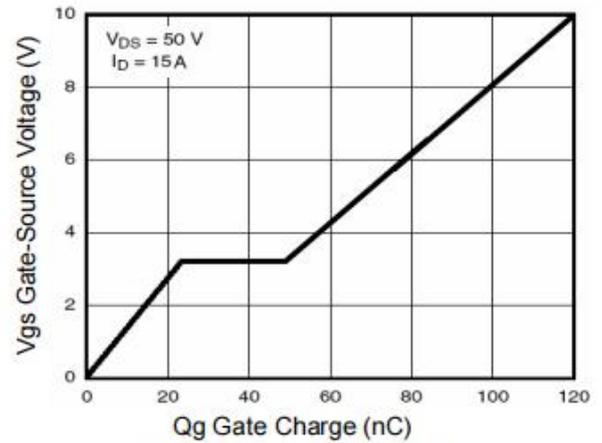


Figure 5 Gate Charge

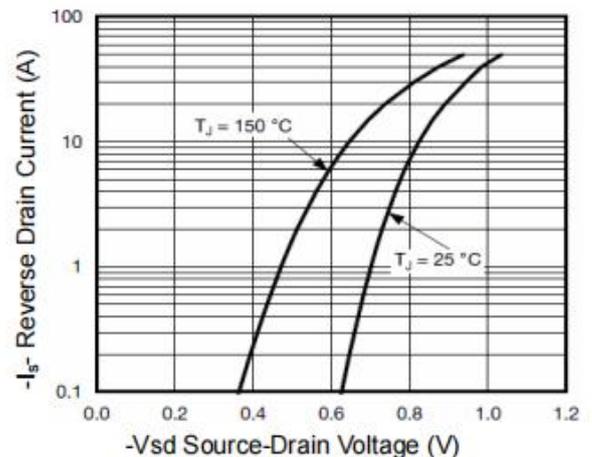


Figure 6 Source- Drain Diode Forward



- Typical Electrical and Thermal Characteristics (Curves)

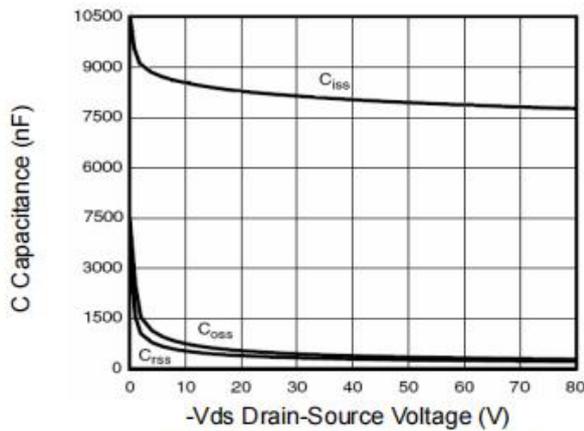


Figure 7 Capacitance vs Vds

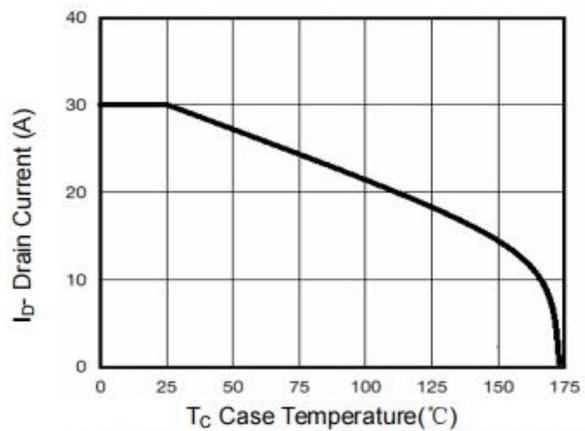


Figure 9 Drain Current vs Case Temperature

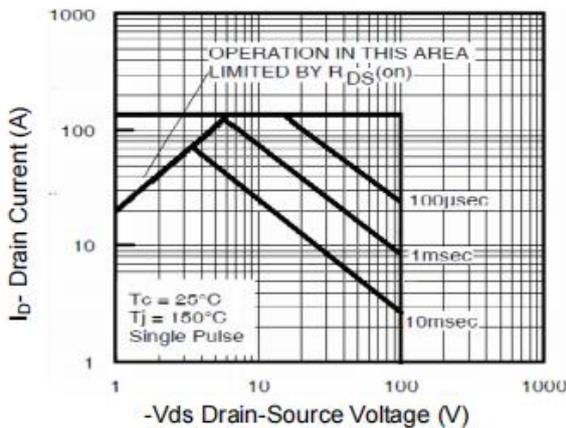


Figure 8 Safe Operation Area

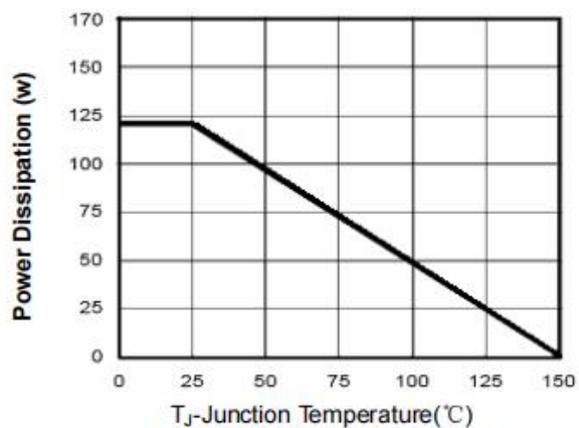


Figure 10 Power De-rating

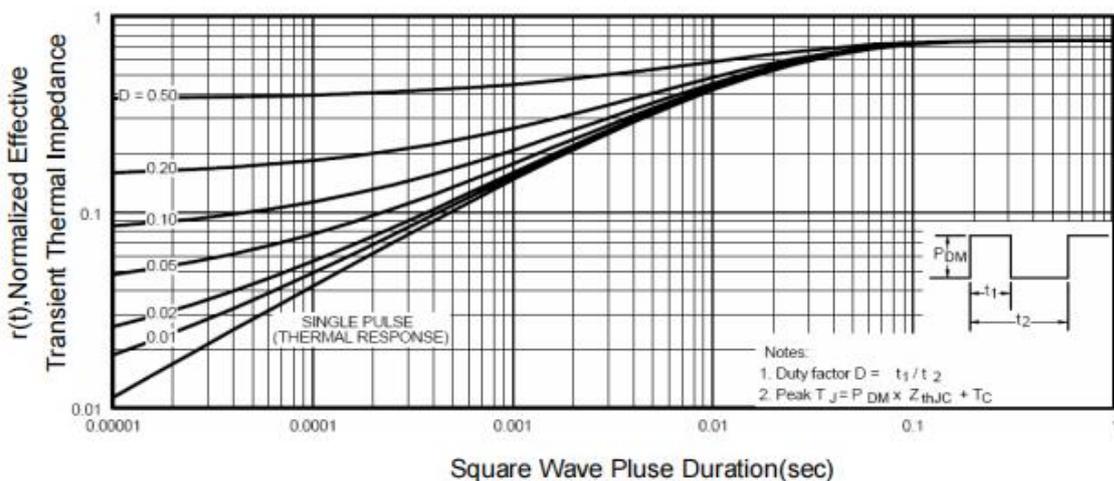
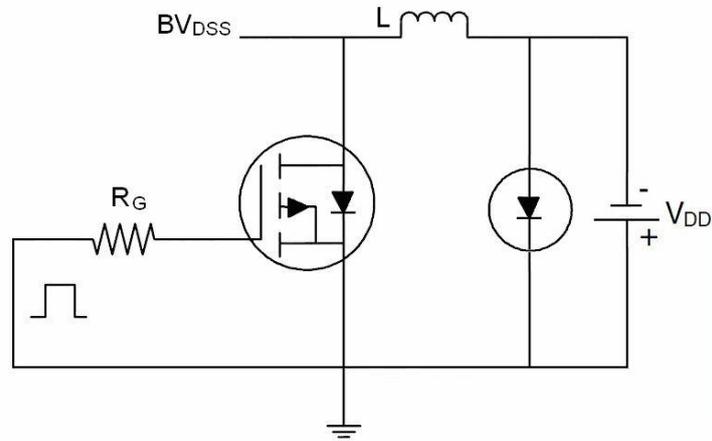


Figure 11 Normalized Maximum Transient Thermal Impedance

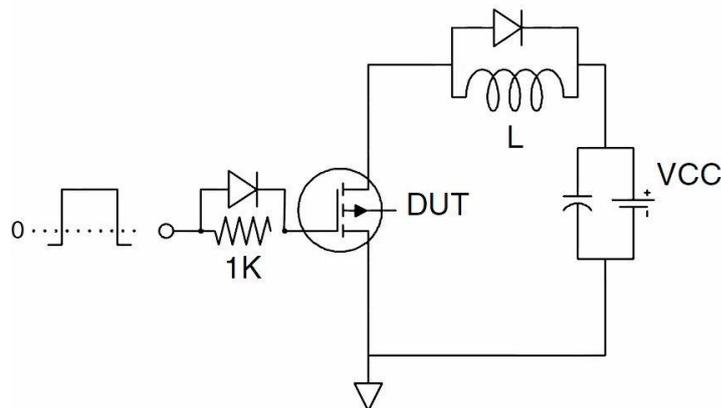


● Test Circuit

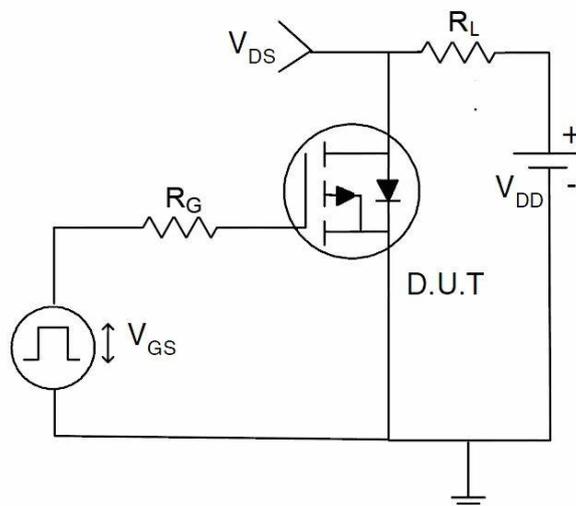
EAS Test Circuit



Gate Charge Test Circuit

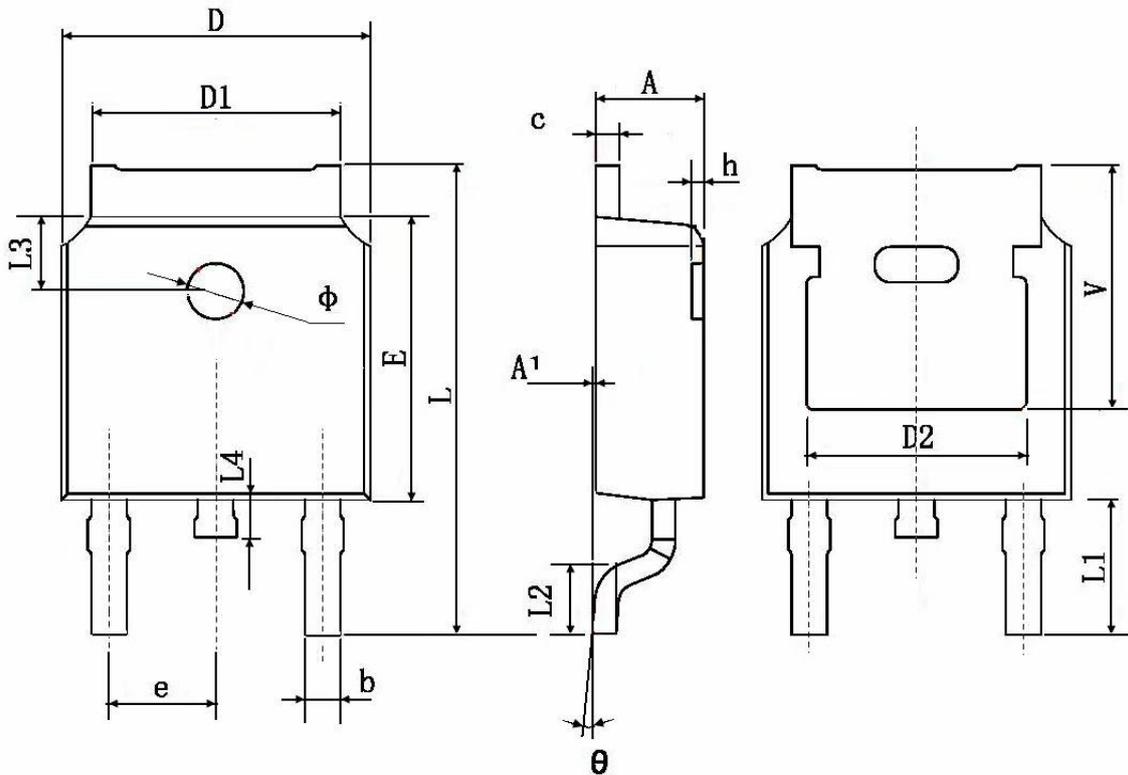


Switch Time Test Circuit





● TO-252 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
b	0.660	0.860	0.026	0.034
c	0.460	0.580	0.018	0.023
D	6.500	6.700	0.256	0.264
D1	5.100	5.460	0.201	0.215
D2	4.830 TYP.		0.190 TYP.	
E	6.000	6.200	0.236	0.244
e	2.186	2.386	0.086	0.094
L	9.800	10.400	0.386	0.409
L1	2.900 TYP.		0.114 TYP.	
L2	1.400	1.700	0.055	0.067
L3	1.600 TYP.		0.063 TYP.	
L4	0.600	1.000	0.024	0.039
φ	1.100	1.300	0.043	0.051
θ	0°	8°	0°	8°
h	0.000	0.300	0.000	0.012
V	5.350 TYP.		0.211 TYP.	